

MC14106B

Hex Schmitt Trigger

The MC14106B hex Schmitt Trigger is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. These devices find primary use where low power dissipation and/or high noise immunity is desired. The MC14106B may be used in place of the MC14069UB hex inverter for enhanced noise immunity or to “square up” slowly changing waveforms.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

Features

- Increased Hysteresis Voltage Over the MC14584B
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- Pin-for-Pin Replacement for CD40106B and MM74C14
- Can Be Used to Replace the MC14584B or MC14069UB
- Pb-Free Packages are Available

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V_{in}, V_{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to $V_{DD} + 0.5$	V
I_{in}, I_{out}	Input or Output Current (DC or Transient) per Pin	± 10	mA
P_D	Power Dissipation, per Package (Note 1)	500	mW
T_A	Ambient Temperature Range	-55 to +125	°C
T_{stg}	Storage Temperature Range	-65 to +150	°C
T_L	Lead Temperature (8-Second Soldering)	260	°C

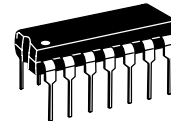
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating: Plastic “P and D/DW” Packages: - 7.0 mW/°C From 65°C To 125°C



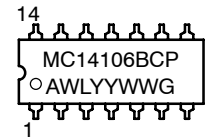
ON Semiconductor®

<http://onsemi.com>

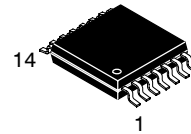
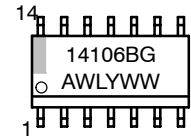


PDIP-14
P SUFFIX
CASE 646

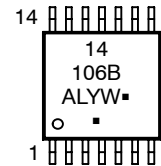
MARKING DIAGRAMS



SOIC-14
D SUFFIX
CASE 751A



TSSOP-14
DT SUFFIX
CASE 948G



- A = Assembly Location
- WL, L = Wafer Lot
- YY, Y = Year
- WW, W = Work Week
- G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

MC14106B

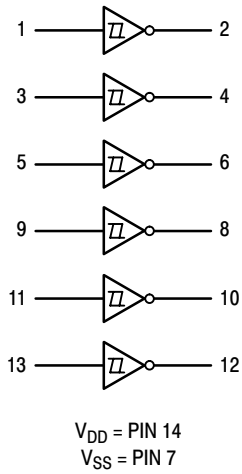


Figure 1. Logic Diagram

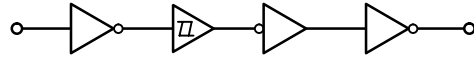


Figure 2. Equivalent Circuit Schematic
(1/6 of Circuit Shown)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14106BCP	PDIP-14	25 Units / Rail
MC14106BCPG	PDIP-14 (Pb-Free)	
MC14106BD	SOIC-14	55 Units / Rail
MC14106BDG	SOIC-14 (Pb-Free)	
MC14106BDR2	SOIC-14	2500 / Tape & Reel
MC14106BDR2G	SOIC-14 (Pb-Free)	
MC14106BDTR2	TSSOP-14*	
MC14106BDTR2G	TSSOP-14*	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

MC14106B

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	- 55°C		25°C			125°C		Unit	
			Min	Max	Min	Typ ⁽²⁾	Max	Min	Max		
Output Voltage $V_{in} = V_{DD}$ $V_{in} = 0$	"0" Level V_{OL}	5.0	-	0.05	-	0	0.05	-	0.05	Vdc	
		10	-	0.05	-	0	0.05	-	0.05		
		15	-	0.05	-	0	0.05	-	0.05		
	"1" Level V_{OH}	5.0	4.95	-	4.95	5.0	-	4.95	-		Vdc
		10	9.95	-	9.95	10	-	9.95	-		
		15	14.95	-	14.95	15	-	14.95	-		
Hysteresis Voltage	V_H ⁽⁵⁾	5.0	0.3	2.0	0.3	1.1	2.0	0.3	2.0	Vdc	
		10	1.2	3.4	1.2	1.7	3.4	1.2	3.4		
		15	1.6	5.0	1.6	2.1	5.0	1.6	5.0		
Threshold Voltage Positive-Going Negative-Going	V_{T+}	5.0	2.2	3.6	2.2	2.9	3.6	2.2	3.6	Vdc	
		10	4.6	7.1	4.6	5.9	7.1	4.6	7.1		
		15	6.8	10.8	6.8	8.8	10.8	6.8	10.8		
	V_{T-}	5.0	0.9	2.8	0.9	1.9	2.8	0.9	2.8		Vdc
		10	2.5	5.2	2.5	3.9	5.2	2.5	5.2		
		15	4.0	7.4	4.0	5.8	7.4	4.0	7.4		
Output Drive Current $(V_{OH} = 2.5 \text{ Vdc})$ $(V_{OH} = 4.6 \text{ Vdc})$ $(V_{OH} = 9.5 \text{ Vdc})$ $(V_{OH} = 13.5 \text{ Vdc})$ $(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Source I_{OH}	5.0	-3.0	-	-2.4	-4.2	-	-1.7	-	mAdc	
		5.0	-0.64	-	-0.51	-0.88	-	-0.36	-		
		10	-1.6	-	-1.3	-2.25	-	-0.9	-		
		15	-4.2	-	-3.4	-8.8	-	-2.4	-		
	Sink I_{OL}	5.0	0.64	-	0.51	0.88	-	0.36	-		mAdc
		10	1.6	-	1.3	2.25	-	0.9	-		
15		4.2	-	3.4	8.8	-	2.4	-			
Input Current	I_{in}	15	-	± 0.1	-	± 0.00001	± 0.1	-	± 1.0	μAdc	
Input Capacitance $(V_{in} = 0)$	C_{in}	-	-	-	-	5.0	7.5	-	-	pF	
Quiescent Current (Per Package)	I_{DD}	5.0	-	0.25	-	0.0005	0.25	-	7.5	μAdc	
		10	-	0.5	-	0.0010	0.5	-	15		
		15	-	1.0	-	0.0015	1.0	-	30		
Total Supply Current (Note 3, 4) (Dynamic plus Quiescent, Per Package) $(C_L = 50 \text{ pF}$ on all outputs, all buffers switching)	I_T	5.0	$I_T = (1.8 \mu\text{A/kHz}) f + I_{DD}$							μAdc	
		10	$I_T = (3.6 \mu\text{A/kHz}) f + I_{DD}$								
		15	$I_T = (5.4 \mu\text{A/kHz}) f + I_{DD}$								

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

3. The formulas given are for the typical characteristics only at 25°C.

4. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk where } I_T \text{ is in } \mu\text{A (per package)}, C_L \text{ in pF, } V = (V_{DD} - V_{SS}) \text{ in volts, } f \text{ in kHz is input frequency, and } k = 0.001.$$

5. $V_H = V_{T+} - V_{T-}$ (But maximum variation of V_H is specified as less than $V_{T+ \text{ max}} - V_{T- \text{ min}}$).

MC14106B

SWITCHING CHARACTERISTICS ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$)

Characteristic	Symbol	V_{DD} Vdc	Min	Typ (6)	Max	Unit
Output Rise Time	t_{TLH}	5.0	–	100	200	ns
		10	–	50	100	
		15	–	40	80	
Output Fall Time	t_{THL}	5.0	–	100	200	ns
		10	–	50	100	
		15	–	40	80	
Propagation Delay Time	t_{PLH} , t_{PHL}	5.0	–	125	250	ns
		10	–	50	100	
		15	–	40	80	

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

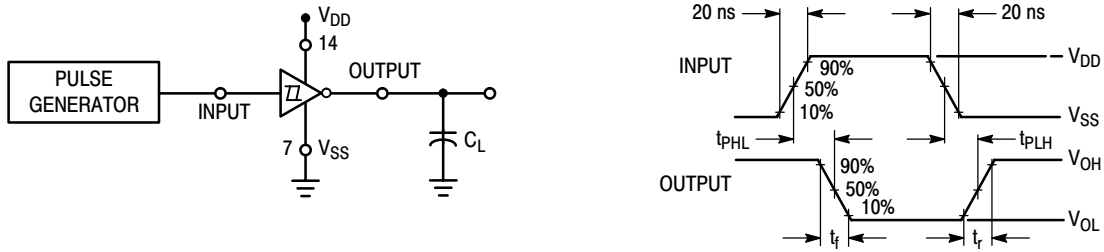


Figure 1. Switching Time Test Circuit and Waveforms

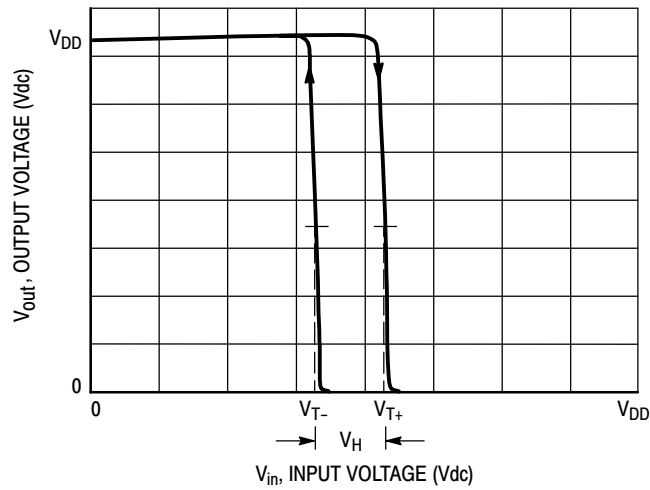


Figure 2. Typical Transfer Characteristics

MC14106B

APPLICATIONS

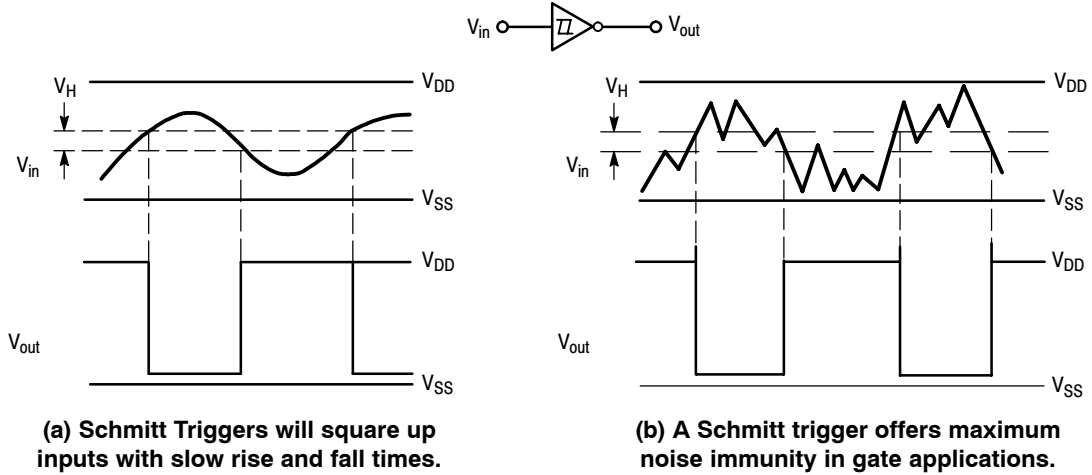


Figure 3.

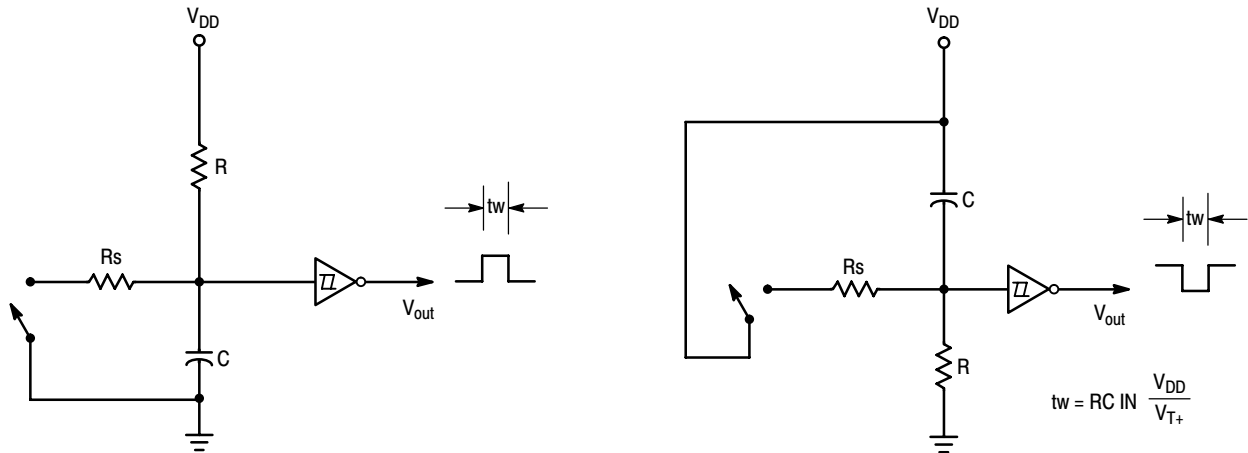


Figure 4. Monostable Multivibrator

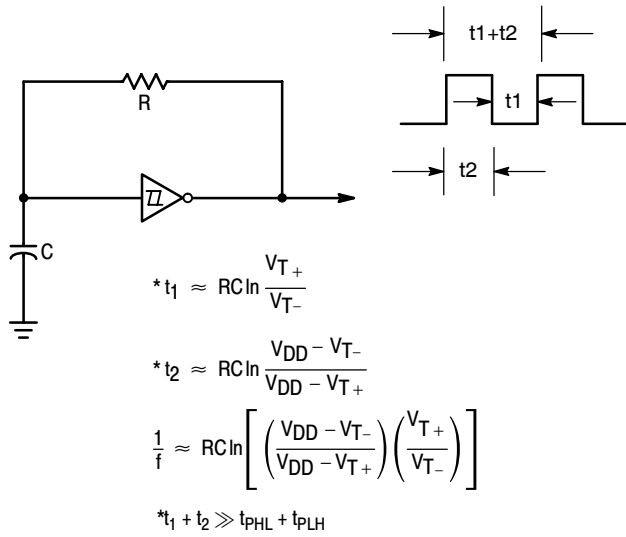


Figure 5. Astable Multivibrator

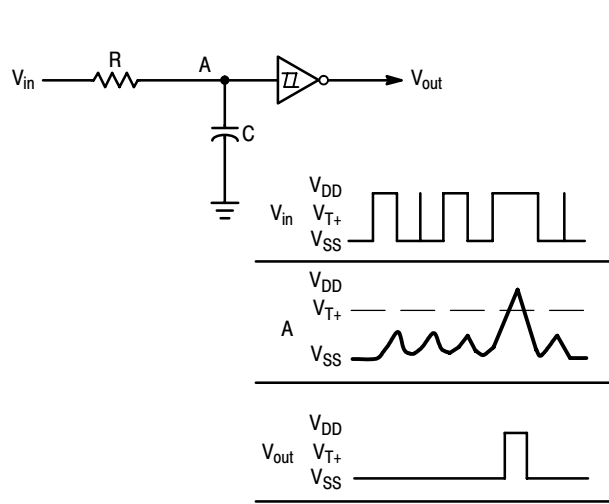


Figure 6. Integrator

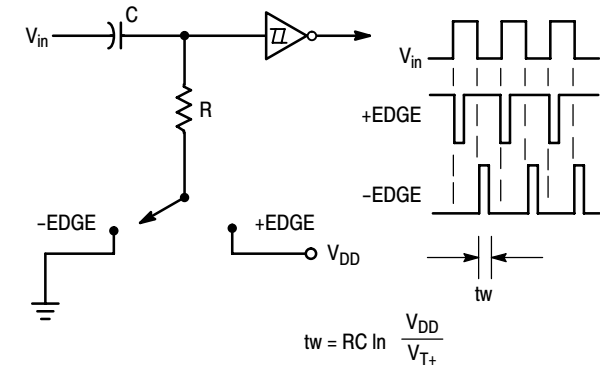


Figure 7. Differentiator

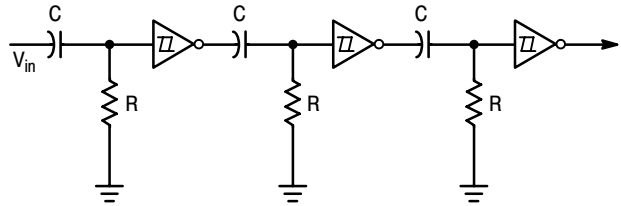
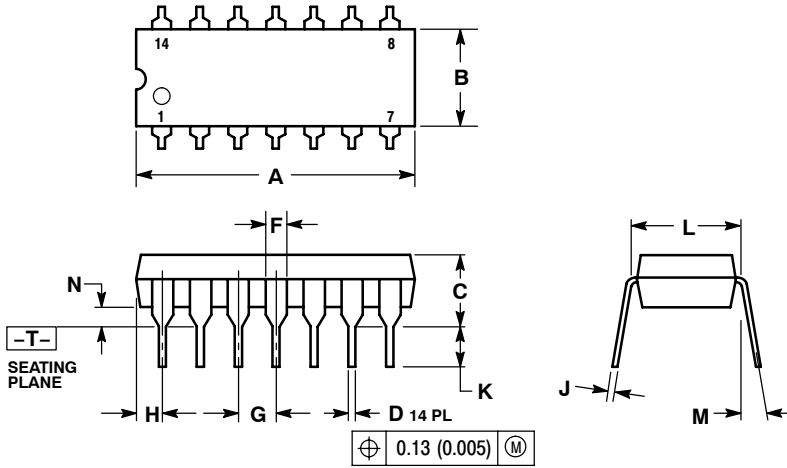


Figure 8. Positive Edge Time Delay Circuit

MC14106B

PACKAGE DIMENSIONS

PDIP-14
CASE 646-06
ISSUE P



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	19.56
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M	---	10°	---	10°
N	0.015	0.039	0.38	1.01

MC14106B

PACKAGE DIMENSIONS

SOIC-14
CASE 751A-03
ISSUE H



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT*



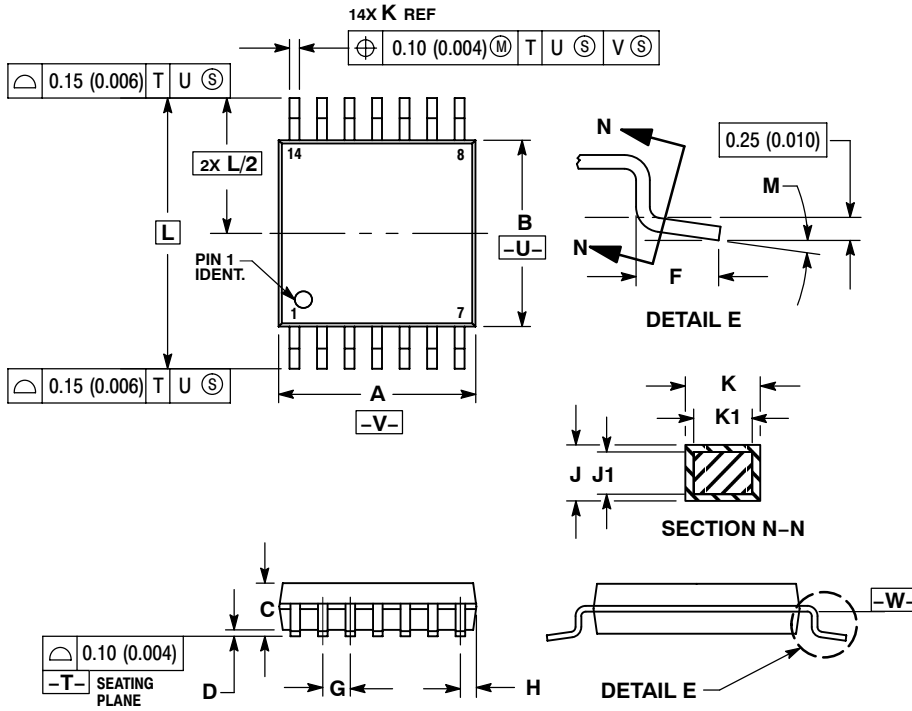
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC14106B

PACKAGE DIMENSIONS

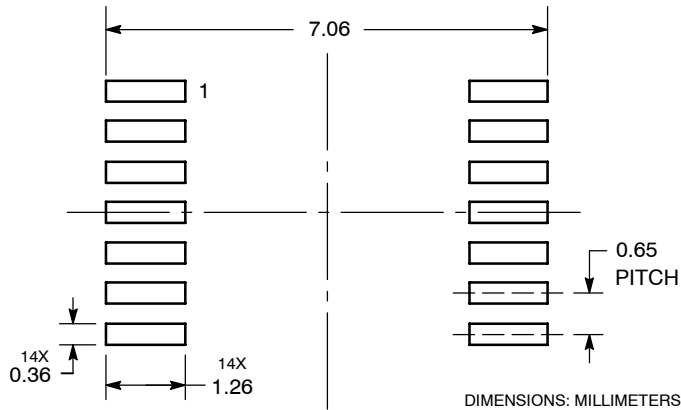
TSSOP-14
CASE 948G-01
ISSUE B



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0° 8°		0° 8°	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and **ON** are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free
USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com
Order Literature: <http://www.onsemi.com/orderlit>

For additional information, please contact your local
Sales Representative